IXYS
INTEGRATED CIRCUITS DIVISION

CPC1973
Power SIP Relay

Parameter	Rating	Units
Blocking Voltage	400	V_P
Load Current	0.35	A_{rms}
On-Resistance (max)	5	Ω

Features

- Power SIP Package
- Handle Load Currents Up to 0.35A_{rms}
- High Reliability
- Low Drive Power Requirements
- Arc-Free With No Snubbing Circuits
- 2500V_{rms} Input/Output Isolation
- No EMI/RFI Generation
- Flammability Rating UL 94 V-0

Applications

- Industrial Controls
- Motor Control
- Robotics
- Medical Equipment—Patient/Equipment Isolation
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- IC Equipment
- Home Appliances

Description

IXYS Integrated Circuits brings OptoMOS® technology, reliability and compact size to a new family of high power solid state relays. As part of that family, the CPC1973 is a 1-Form-A solid state relay.

The CPC1973 employs optically coupled MOSFET technology to provide 2500V_{rms} of input to output isolation.

The optically coupled outputs, that use patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

The combination of low on-resistance and high load current handling capabilities makes the relay suitable for a variety of high performance switching applications.

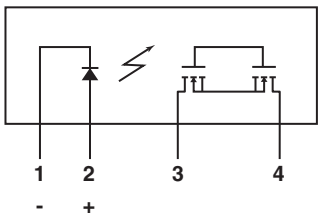
Approvals

- UL 508 Recognized Component: File # E69938
- CSA Certified Component: Certificate # 1172007

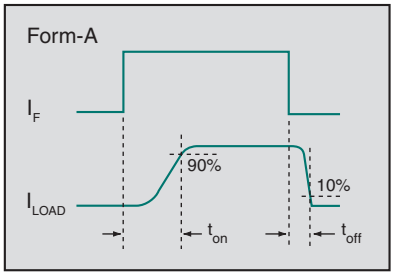
Ordering Information

Part #	Description
CPC1973Y	4-Pin (8-Pin Body) Power SIP Package (25 per tube)

Pin Configuration



Switching Characteristics of Normally Open (Form A) Devices



Absolute Maximum Ratings (@ 25˚ C)

Parameter	Ratings	Units
Blocking Voltage	400	V_P
Reverse Input Voltage	5	V
Input control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation [1]	150	mW
Total Power Dissipation [2]	2400	mW
Isolation voltage Input to Output	2500	V_{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

[1] Derate linearly 1.33 mw / °C
[2] Derate linearly 20 mw / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics @ 25°C						
Load Current, Continuous	free air	I_L	-	-	0.35	A_{rms}
Peak	t≤10ms	I_{LPK}	-	-	3.5	
On-Resistance[1]	I_L=350mA	R_{ON}	-	3.4	5	Ω
Off-State Leakage Current	V_L=400V	I_{LEAK}	-	-	1	µA
Switching Speeds Turn-On	I_F=10mA, V_L=10V	t_{ON}	-	-	5	ms
Turn-Off		t_{OFF}	-	-	3	ms
Input Characteristics @ 25°C						
Input Control Current to Activate	I_L=350mA	I_F	-	-	10	mA
Input Control Current to Deactivate	-	I_F	-	-	-	mA
Input Voltage Drop	I_F=10mA	V_F	0.9	1.35	1.56	V
Reverse Input Current	V_R=5V	I_R	-	-	10	µA
Input/Output Characteristics @ 25°C						
Capacitance Input/Output	V_{IO}=0V, f=1MHz	C_{IO}	-	2	-	pF

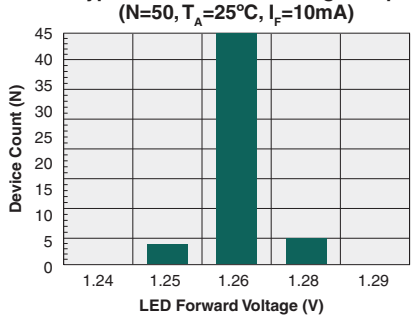
[1] Measurement taken within 1 second of on time.

Thermal Characteristics

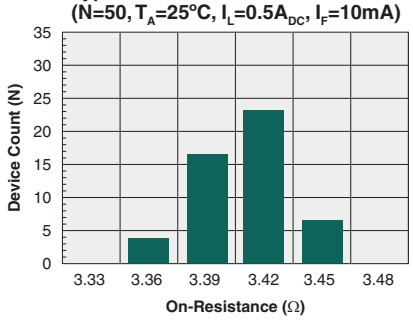
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Thermal Impedance (junction to case)	-	$R_{\theta JC}$	-	1.5	-	°C/W

PERFORMANCE DATA*

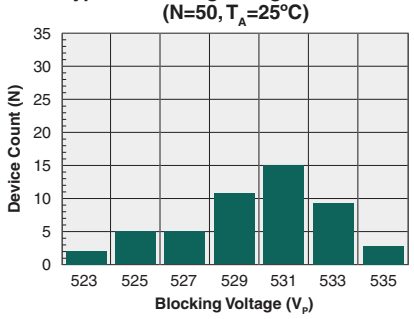
Typical LED Forward Voltage Drop
(N=50, T_A=25°C, I_F=10mA)



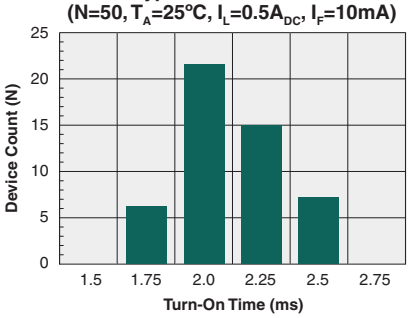
Typical On-Resistance Distribution
(N=50, T_A=25°C, I_L=0.5A_{DC}, I_F=10mA)



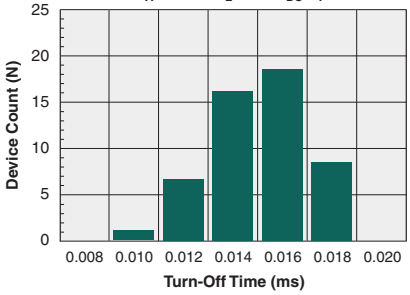
Typical Blocking Voltage Distribution
(N=50, T_A=25°C)



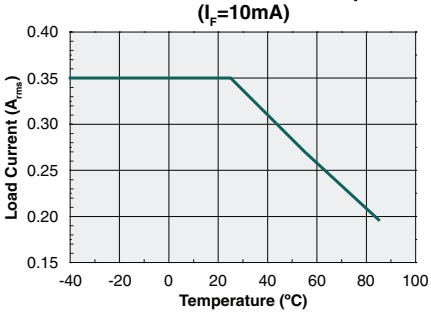
Typical Turn-On Time
(N=50, T_A=25°C, I_L=0.5A_{DC}, I_F=10mA)



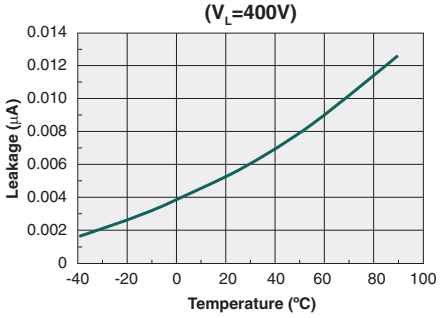
Typical Turn-Off Time
(N=50, T_A=25°C, I_L=0.5A_{DC}, I_F=10mA)



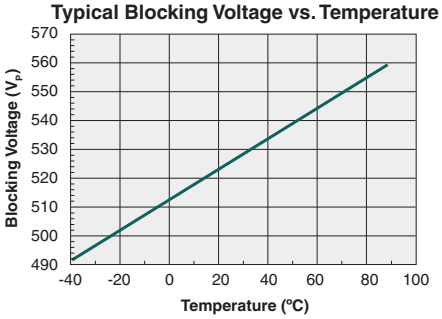
Maximum Load Current vs. Temperature
(I_F=10mA)



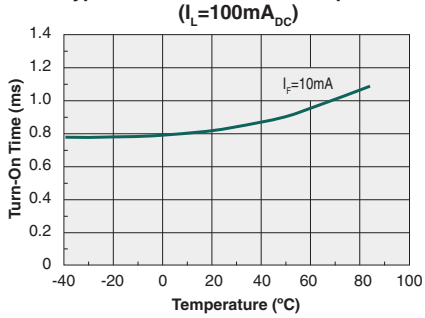
Typical Leakage vs. Temperature
Measured Across Pins 3&4
(V_L=400V)



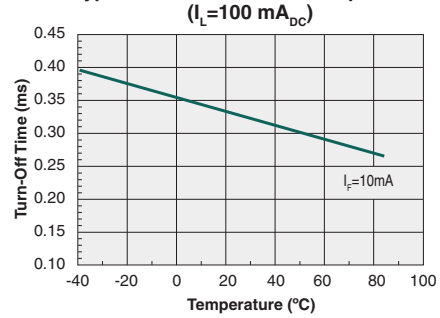
Typical Blocking Voltage vs. Temperature



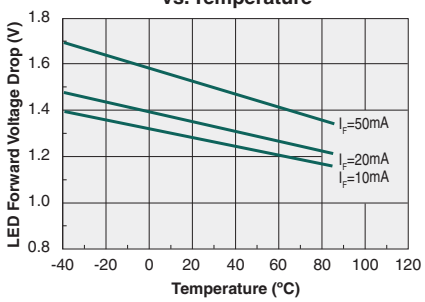
Typical Turn-On Time vs. Temperature
(I_L=100mA_{DC})



Typical Turn-Off Time vs. Temperature
(I_L=100 mA_{DC})



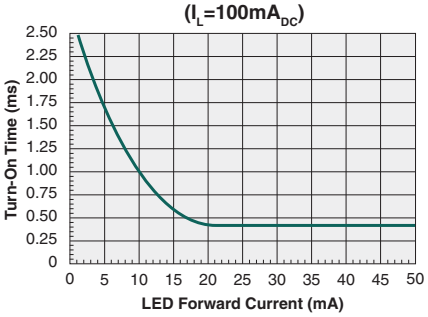
Typical LED Forward Voltage Drop
vs. Temperature



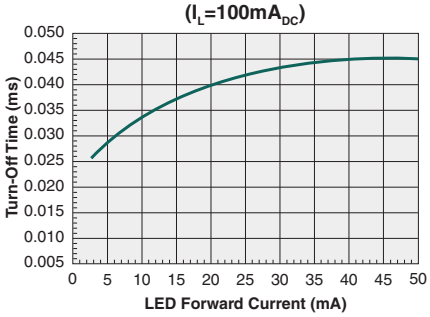
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA*

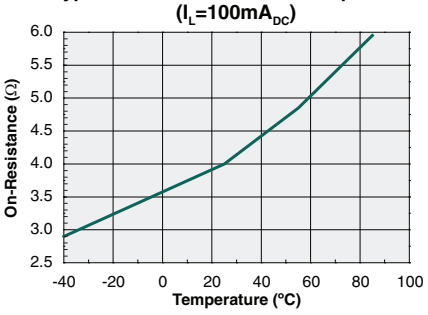
Typical Turn-On Time vs. LED Forward Current (I_L=100mA$_{DC}$)



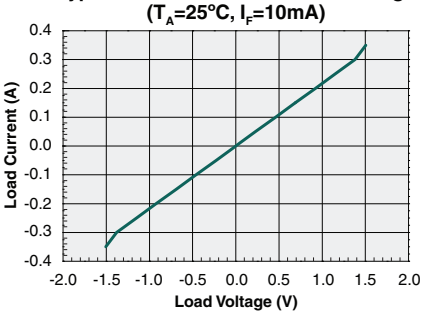
Typical Turn-Off Time vs. LED Forward Current (I_L=100mA$_{DC}$)



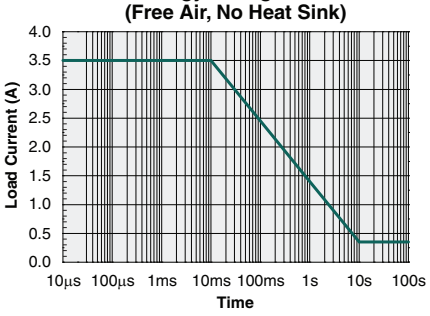
Typical On-Resistance vs. Temperature (I_L=100mA$_{DC}$)



Typical Load Current vs. Load Voltage (T_A=25°C, I_F=10mA)



Energy Rating Curve (Free Air, No Heat Sink)



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For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1973Y	MSL 1

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

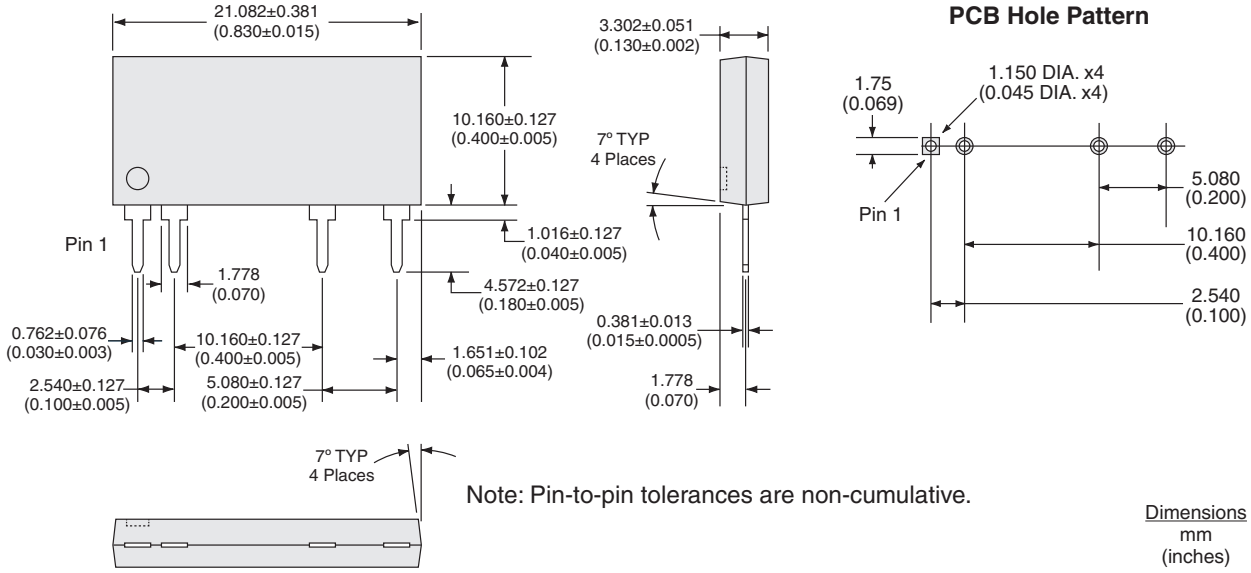
Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)°C or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Classification Temperature (T_c)	Dwell Time (t_p)	Max Reflow Cycles
CPC1973Y	245°C	30 seconds	1

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

MECHANICAL DIMENSIONS



Note: Pin-to-pin tolerances are non-cumulative.

Dimensions
mm
(inches)

For additional information please visit our website at: www.ixysic.com

Specification: DS-CPC1973-R05

6/29/2018